

PRODUCT / PROCESS CHANGE NOTIFICATION

1. PCN basic data

1.1 Company	 STMicroelectronics International N.V
1.2 PCN No.	EMBEDDED PROCESSING/25/15272
1.3 Title of PCN	Chinese Supply Chain, as additional source, for STM32H75x/74x products in BGA packages.
1.4 Product Category	STM32H74x, STM32H75x
1.5 Issue date	2025-07-14

2. PCN Team

2.1 Contact supplier	
2.1.1 Name	ROBERTSON HEATHER
2.1.2 Phone	+1 8475853058
2.1.3 Email	heather.robertson@st.com
2.2 Change responsibility	
2.2.1 Product Manager	Patrick AIDOUNE
2.1.2 Marketing Manager	Veronique BARLATIER
2.1.3 Quality Manager	Pascal NARCHE

3. Change

3.1 Category	3.2 Type of change	3.3 Manufacturing Location
Transfer	Line transfer for a full process or process brick (process step, control plan, recipes) from one site to another site: Wafer fabrication (SOP 2617)	HHGrace Wuxi (China) & JSCC JiangYin (China)

4. Description of change

	Old	New
4.1 Description	<p>. Front-end sources for M40 Die 450 cut2.2 : Existing : - ST Crolles (France) CR300 revision V</p> <p>. Back-end sources for TFBGA 14X14 and UFBGA 10X10 packages: Existing : - Amkor ATP (Philippines) and ASE KaoHsiung (Taiwan)</p>	<p>. Front-end sources for M40 Die 450 cut2.2 : Existing : - ST Crolles (France) CR300 revision V Additional : - HHGrace Wuxi fab7 (China) revision 2 - HHGrace Wuxi fab9 (China) revision 3</p> <p>. Back-end sources for TFBGA 14X14 and UFBGA 10X10 packages : Existing : - Amkor ATP (Philippines) and ASE KaoHsiung (Taiwan) Additional : - JSCC JiangYin (China)</p>
4.2 Anticipated Impact on form,fit, function, quality, reliability or processability?	No change on Form, Fit or Function - same datasheet.	

5. Reason / motivation for change

5.1 Motivation	Due to the success on the market of STM32 devices, ST Microcontrollers Division decided to qualify an additional front-end site to maintain state of the art service level to our customers thanks to extra capacity.
5.2 Customer Benefit	MANUFACTURING FLEXIBILITY

6. Marking of parts / traceability of change

6.1 Description	Change is visible through diffusion traceability plant, in the marking: - "VQ" for ST Crolles (France) - "2E" for HHGrace Wuxi (China) Please refer to PCN 15272 – Additional information attached document.
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7. Timing / schedule

7.1 Date of qualification results	2025-10-30
7.2 Intended start of delivery	2025-12-15

7.3 Qualification sample available?	Upon Request
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8. Qualification / Validation			
8.1 Description	15272 MDRF-GPAM-RER2511 PCN15272 - HHGrace (China) STM32H74x_H75x M40 technol for TFBGA_UFBGA in JSCC - RER plan.pdf		
8.2 Qualification report and qualification results	Available (see attachment)	Issue Date	2025-07-14

9. Attachments (additional documentations)			
15272 Public product.pdf 15272 MDRF-GPAM-RER2511 PCN15272 - HHGrace (China) STM32H74x_H75x M40 technol for TFBGA_UFBGA in JSCC - RER plan.pdf 15272 _Additional information.pdf			

10. Affected parts		
10.1 Current		10.2 New (if applicable)
10.1.1 Customer Part No	10.1.2 Supplier Part No	10.1.2 Supplier Part No
	STM32H743IIK6	
	STM32H743XIH6	
	STM32H743XIH6TR	
	STM32H745XGH6	
	STM32H745XIH3	
	STM32H745XIH6	
	STM32H747XIH6	
	STM32H750IBK6	
	STM32H750XBH6	
	STM32H753IIK6	
	STM32H753XIH6	
	STM32H753XIH6TR	
	STM32H755XIH3	
	STM32H755XIH6	
	STM32H757XIH6	
	STM32H757XIH6A	

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